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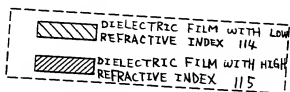
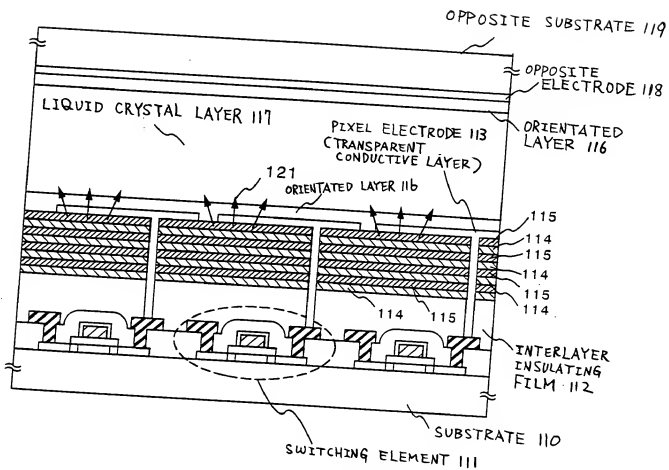
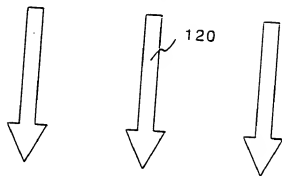
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INCIDENT LIGHT

Fig. 1



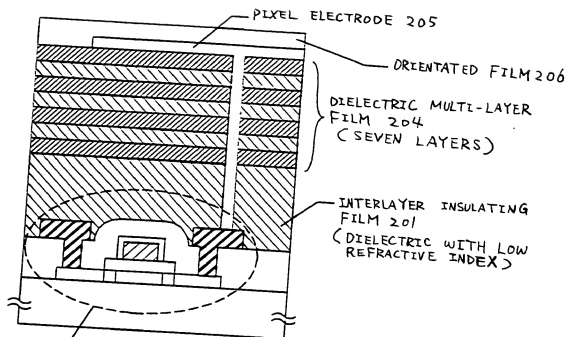


Fig. 2A

EXAMPLE IN WHICH THE NUMBER OF LAYERS IS REDUCED BY USING DIELECTRIC WITH LOW REFRACTIVE INDEX FOR INTERLAYER INSULATING FILM

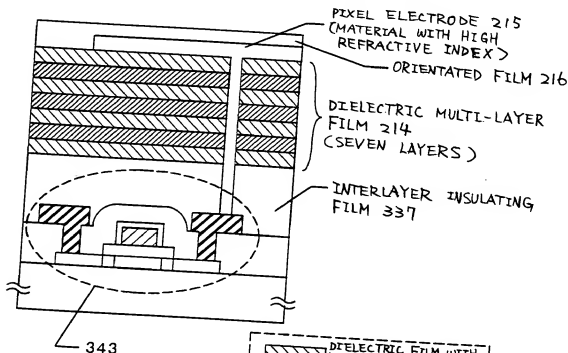
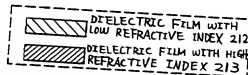


Fig. 2B

EXAMPLE IN WHICH THE NUMBER OF LAYERS IS REDUCED BY USING PIXEL ELECTRODE (ITO) AS MATERIAL WITH HIGH REFRACTIVE INDEX



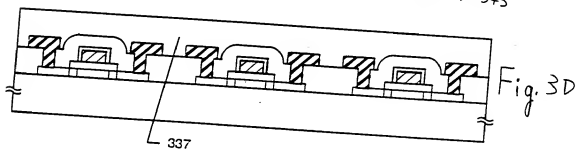
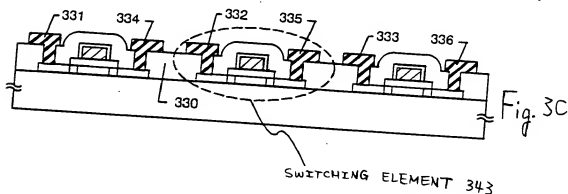
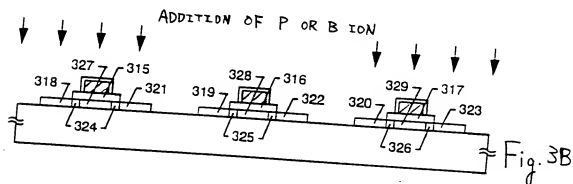
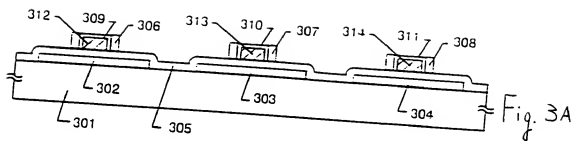


Fig. 4A

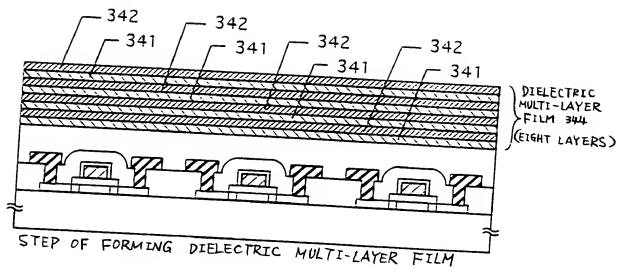


Fig. 4B

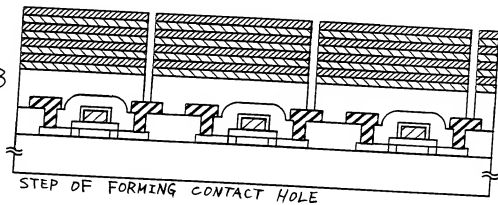
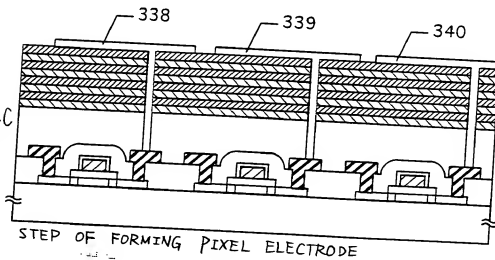


Fig. 4C



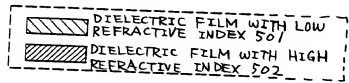
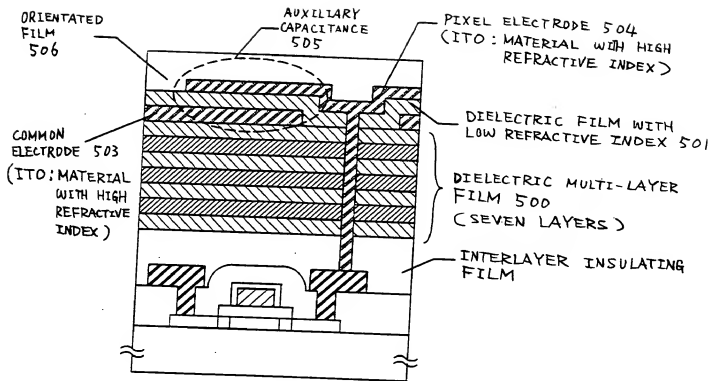


Fig. 5

Fig. 6A (CAPACITIVE CONFIGURATION 1)

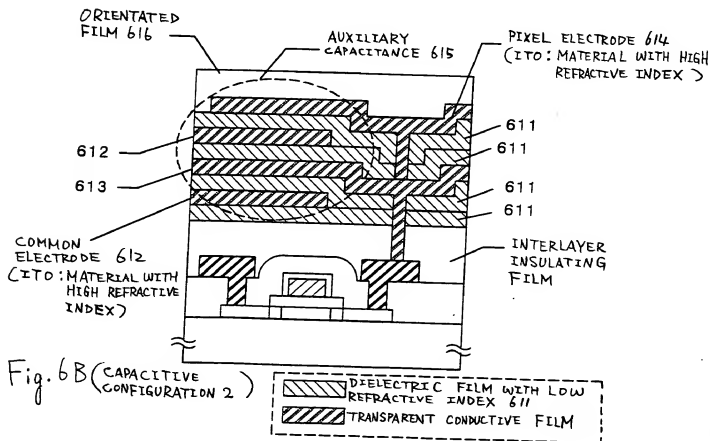
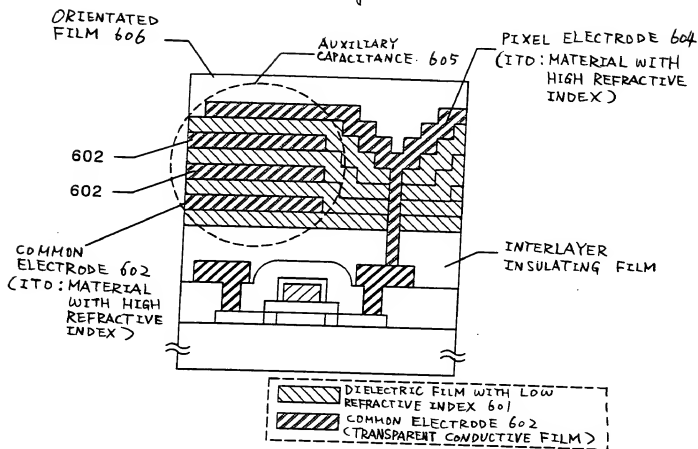


Fig. 7

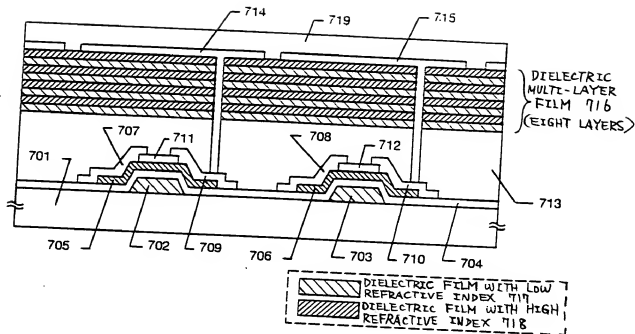
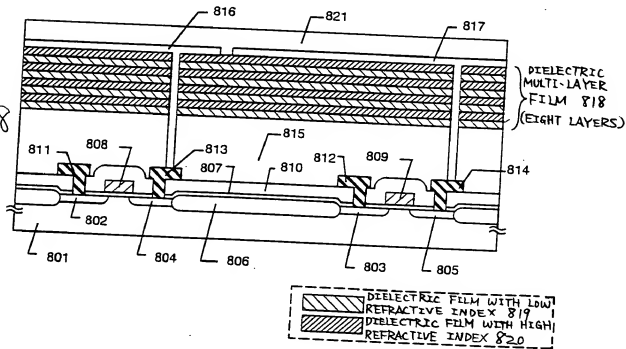


Fig. 8





INCIDENT LIGHT

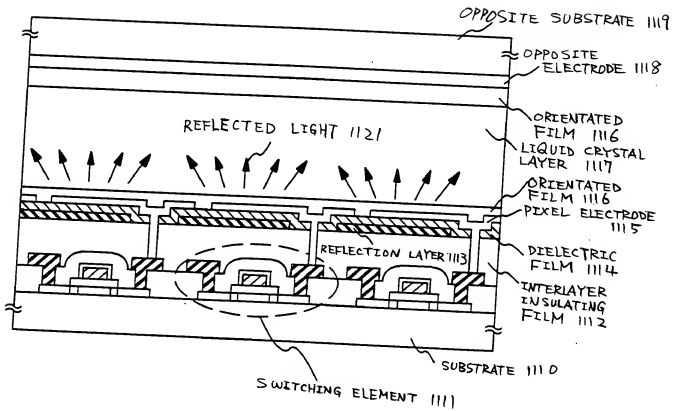
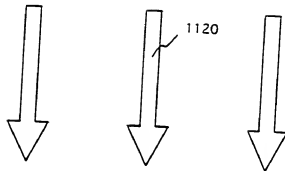
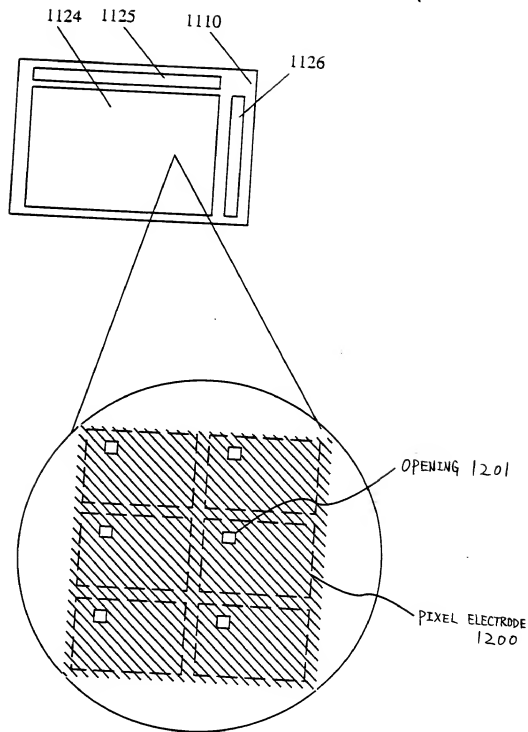



Fig. 9

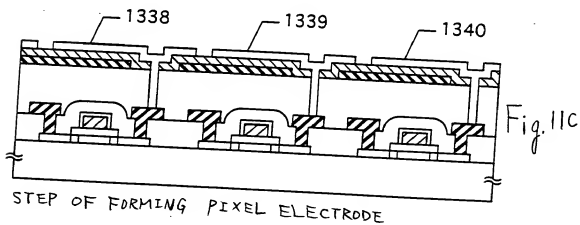
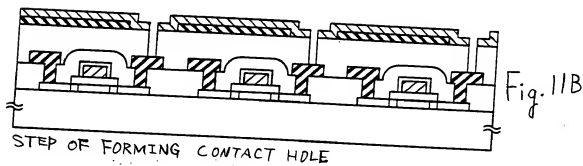
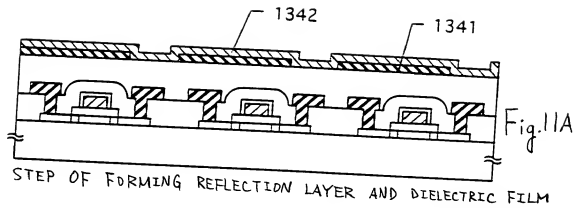
Fig. 10

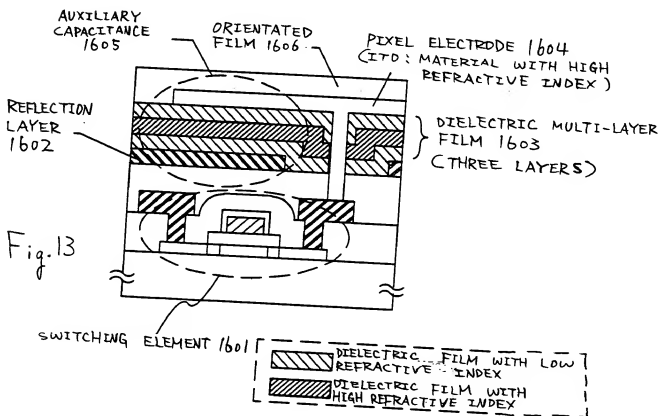
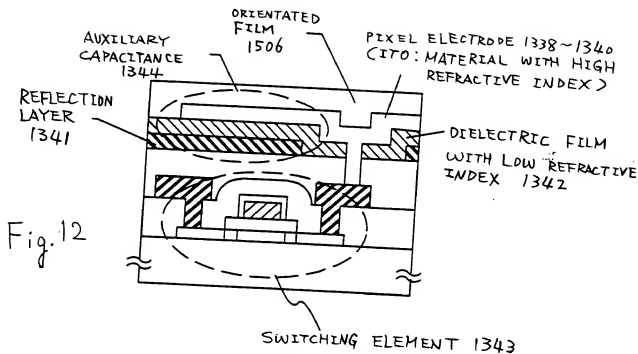


EXAMPLE OF TOP VIEW

 REFLECTION LAYER 1202  
(REFLECTION AREA)

0011070-051209







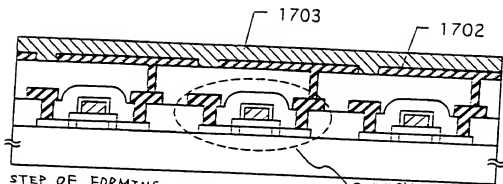


Fig. 15A

STEP OF FORMING CAPACITANCE ELECTRODE 1702 AND DIELECTRIC FILM 1703

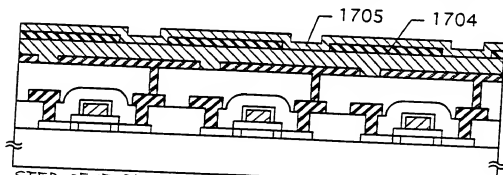


Fig. 15B

STEP OF FORMING REFLECTION LAYER 1704 AND DIELECTRIC FILM 1705

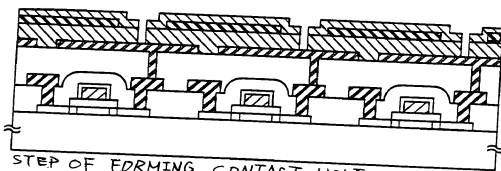


Fig. 15C

STEP OF FORMING CONTACT HOLE

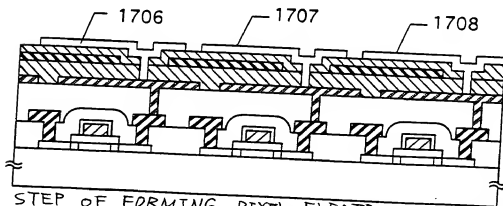


Fig. 15D

STEP OF FORMING PIXEL ELECTRODES 1706 ~ 1708

0011020-01700

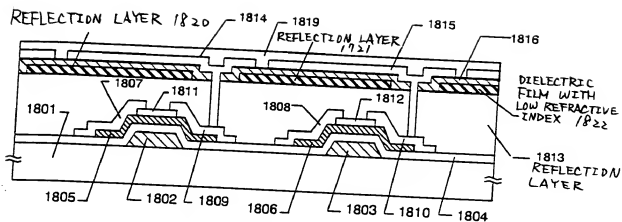


Fig. 16

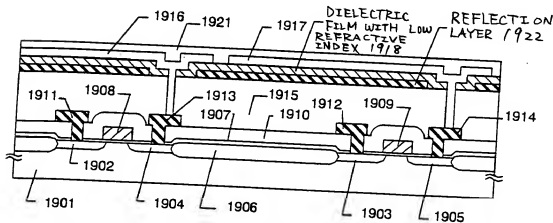


Fig. 17

Fig. 18A

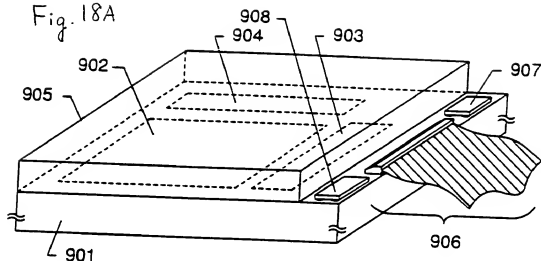
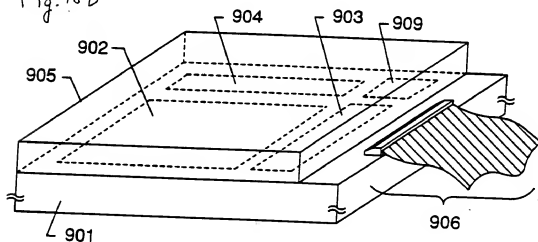


Fig. 18B



- 901: ACTIVE MATRIX SUBSTRATE 902: PIXEL MATRIX CIRCUIT  
 903: SOURCE-SIDE DRIVER CIRCUIT 904: GATE-SIDE DRIVER CIRCUIT  
 905: OPPOSING SUBSTRATE 906: FPC  
 907, 908: IC CHIP 909: LOGIC CIRCUIT



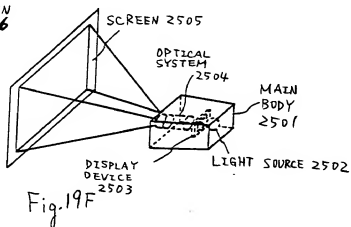
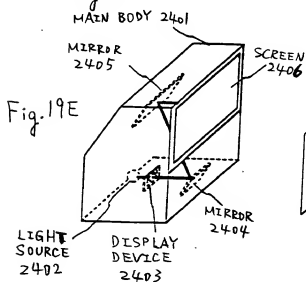
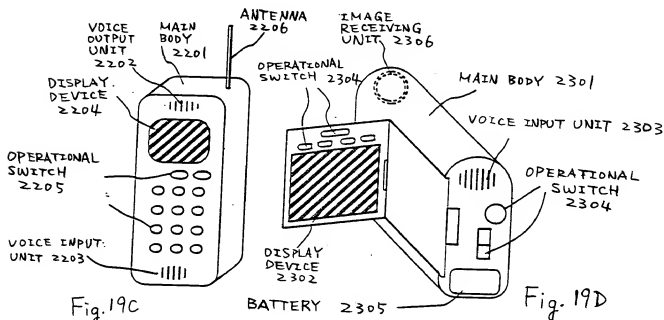
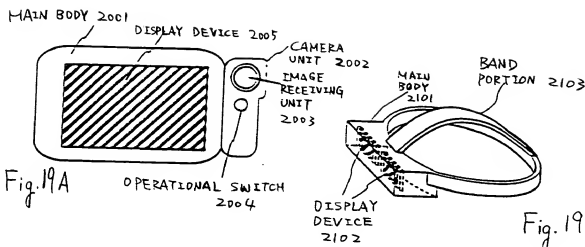
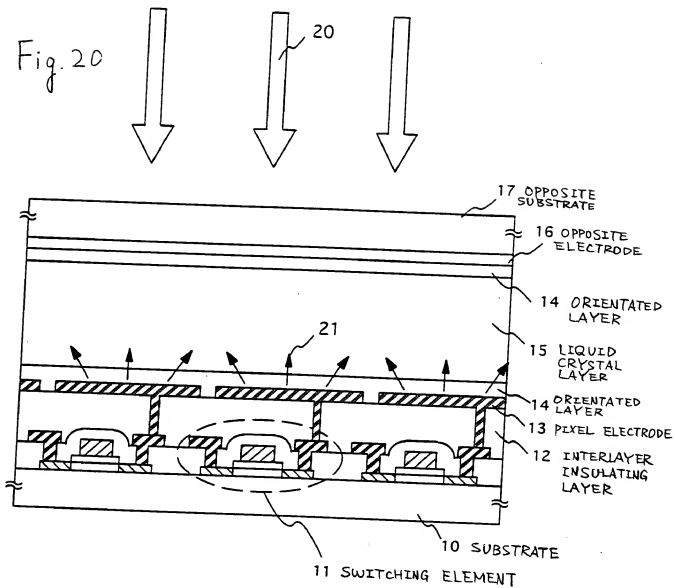


Fig. 20



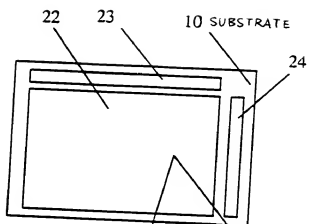
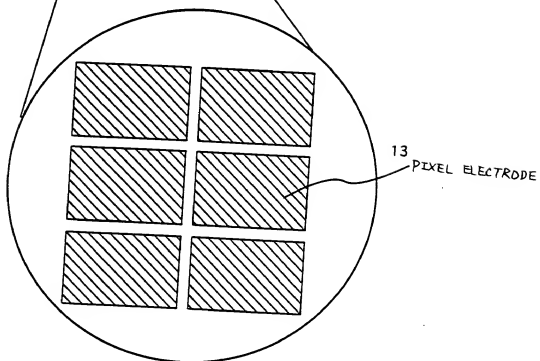


Fig. 21



### EXAMPLE OF TOP VIEW

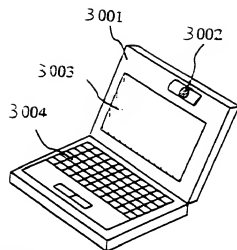


FIG. 11A

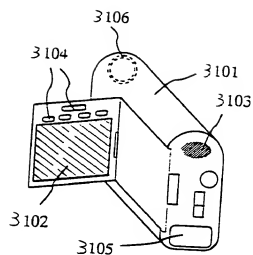


FIG. 22B

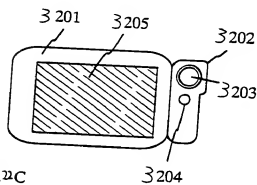


FIG. 2C

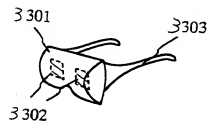


FIG. 22D

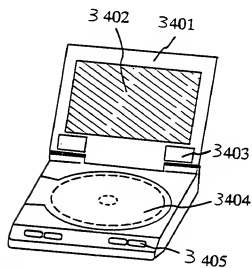


FIG. 22 E

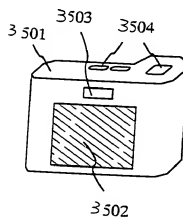


FIG.22F

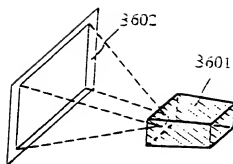


FIG. 23A

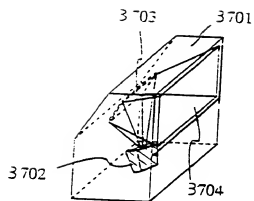


FIG.23B

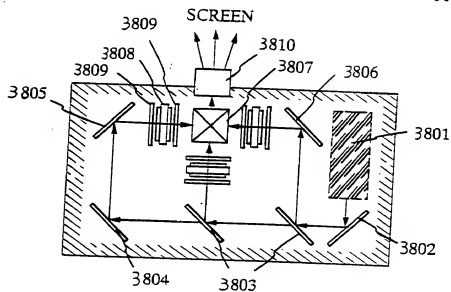


FIG.23C

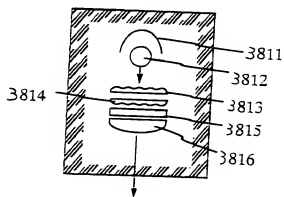


FIG. 23D

